

	Hits	Search Text	DBs	Time Stamp
1	2	"20030003180"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:20
2	2	"20030003380"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:21
3	2	"20030003405"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:21
4	2	"20030043360"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:21
5	2	"20030068584"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:21
6	2	"20030072926"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:21
7	2	"20030077418"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:22
8	2	"20030089999"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:22
9	2	"20030092220"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:22

	Hits	Search Text	DBs	Time Stamp
10	2	"20020093173"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:22
11	2	"20030102566"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:22
12	2	"20030129787"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:22
13	2	"20030151167"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:23
14	2	"20030201531"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:23
15	2	"20030203158"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:23
16	2	"20030207213"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:31
17	534	chip?scale adj package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:47
18	23	("3978578" "4033027" "5157001" "5462636" "5682065" "5742094" "5933713" "5956605" "6210993" "6326698" "6432752").pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:35

	Hits	Search Text	DBs	Time Stamp
19	28	("6251488" "6259962" "6268584" "6337122" "6391251" "6482576" "6524346" "6544821" "6544902" "6549821" "6562278" "6585927" "6593171" "6635333").pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:36
20	2	"20020066966"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:37
21	2	"20020098623"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:37
22	2	"20020171177"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:38
23	2	"20020182782"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:38
24	2	"20040165362"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:39
25	2	"20040000744"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:40
26	2	"20040142058"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:40
27	6	("6875640" "6762502" "6890801").pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:41

	Hits	Search Text	DBs	Time Stamp
28	20	"20020066966" "20020098623" "50020171177" "200182782" "20030003180" "20030003380" "20030003405" "20030043360" "20030068584" "20030068584" "20030072926" "20030077418"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:45
29	16	"20030089999" "20030092220" "20030093173" "20030102566" "20030129787" "20090151167" "20030201531" "20030203158" "20030207213"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:46
30	208	chip?scale adj package and semiconductor adj die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:48
31	3	chip?scale adj package and semiconductor adj die and (cut cutting) and wafer and (etch etching etched) with semiconductor adj die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 11:49
32	9	("5742094").URPN.	USPAT	2005/07/08 12:05
33	7	("4665426" "4843037" "4970571" "5024970" "5055906" "5136364" "5157001").PN.	US-PGPUB; USPAT; USOCR	2005/07/08 12:28
34	7	("4665426" "4843037" "4970571" "5024970" "5055906" "5136364" "5157001").PN.	US-PGPUB; USPAT; USOCR	2005/07/08 12:29
35	82	chip?scale adj package and semiconductor adj die and (cut cutting) and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 12:30
36	45	chip?scale adj package and semiconductor adj die and (cut cutting) with wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/25 14:46
37	1571	farnworth.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 12:41

	Hits	Search Text	DBs	Time Stamp
38	692	S41 and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 12:41
39	592	S41 and wafer and die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 12:41
40	432	S41 and wafer and die and (etch etching etched cut cutting)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 12:42
41	429	S41 and wafer and die and (etch etching etched cut cutting) and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 12:42
42	21	S28 and S41	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/08 12:42
43	3	("5977641" "6064114" "6187615").PN.	US-PGPUB; USPAT; USOCR	2005/07/23 19:06
44	8	chip?scale adj package and semiconductor adj die and (cut cutting) with wafer same (etch etching etched)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/23 19:14
45	26	(chip?scale or chip adj scale) adj package and semiconductor adj die and (cut cutting) with wafer same (etch etching etched)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/23 20:44
46	12	(chip?scale or chip adj scale) adj package and semiconductor adj die and (cut cutting) with wafer same (clean cleaning cleaned)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/23 19:19

	Hits	Search Text	DBs	Time Stamp
47	132	semiconductor adj die and (cut cutting) with wafer same (etch etching etched)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/23 19:19
48	38	semiconductor adj die and (cut cutting) with wafer same (clean cleaning cleaned)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/23 19:19
49	0	semiconductor adj die and (cut cutting) with wafer with (etch etching etched) with (clean cleaning cleaned)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/23 19:25
50	132	semiconductor adj die and (cut cutting) with wafer same (etch etching etched)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/23 19:25
51	0	semiconductor adj die and (cut cutting) with wafer same (etch etching etched) with (clean cleaning cleaned)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/23 19:25
52	68	semiconductor adj die and (cut cutting) with wafer with (etch etching etched)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/23 19:25
53	260	wafer adj scribing	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/23 20:43
54	7	wafer adj scribing and wafer with (cut cutting) same (etch etching etched) with (remove removing removed)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/23 19:40

	Hits	Search Text	DBs	Time Stamp
55	27	("4610079" "4670088" "5143865" "5496775" "5554887" "5703406" "5824569" "5834843" "5844779" "5867417" "5908317" "5933713" "5969426" "5977641" "6020629" "6054772" "6077380" "6097098" "6107164" "6137164" "6150717" "6153448" "6181569" "6208018" "6297553" "6331450" "6379999").PN. OR ("6717245").URPN.	US-PGPUB; USPAT; USOCR	2005/07/23 20:41
56	0	wafer adj scribing and polymer same curing same (spraying or spin adj coating) and bump	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/23 20:44
57	0	wafer adj scribing and polymer same curing same (spraying or spin adj coating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/23 20:44
58	20	(chip?scale or chip adj scale) adj package and semiconductor adj die and polymer and curing and (spraying or spin adj coating or spin?coating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/23 21:00
59	15	(chip?scale or chip adj scale) adj package and semiconductor adj die and polymer and curing and (spraying or spin adj coating or spin?coating) and bump	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/23 20:47
60	57	semiconductor adj die and polymer and curing and (spraying or spin adj coating or spin?coating) and bump	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/23 20:47

	Hits	Search Text	DBs	Time Stamp
61	2	"6762502".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/23 20:56
62	0	("6762502").URPN.	USPAT	2005/07/23 20:56
63	53	("20010038144" "20020098623" "4862245" "5173220" "5209390" "5264061" "5278442" "5304842" "5477086" "5484314" "5551148" "5677576" "5684330" "5705117" "5786626" "5892288" "5894107" "5907477" "5965933" "5999413" "6028354" "6060768" "6084781" "6221697" "6251488" "6259962" "6268584" "6281046" "6288905" "6306752" "6323058" "6326698" "6337122" "6391251" "6432752" "6468891" "6482576" "6489007" "6493932" "6514798" "6524346" "6544821" "6544902" "6549821" "6551917" "6562278" "6585927" "6590295" "6593171" "6600171" "6613662" "6630736" "6635333") .PN.	US-PGPUB; USPAT; USOCR	2005/07/23 20:56
64	95	(chip?scale or chip adj scale) adj package and semiconductor adj die and back with (grind grinding etch etching etched)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/23 21:01
65	63	(chip?scale or chip adj scale) adj package and semiconductor adj die and back with (grind grinding etch etching etched) and back with (layer film)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/25 14:42

	Hits	Search Text	DBs	Time Stamp
66	36	("5138434" "5851911" "5888883" "5904546" "6051875" "6074896" "6087845" "6107164" "6130111" "6150717" "6169329" "6180504" "6233185" "6294837" "6338980" "6353267" "6534387" "6607970" "5686317" "5863813" "5897337" "6013948" "6060373" "6080602" "6107109" "6114240" "6136137" "6153448" "6177295" "6221751" "6281131" "6313531" "6350664" "6524890" "6579748" "6649445") .PN.	US-PGPUB; USPAT; USOCR	2005/07/23 21:02
67	2	"6353267".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/25 14:01
68	14	(chip?scale or chip adj scale) adj package and semiconductor adj die and back with (CMP) and back with (layer film)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/25 14:42
69	0	chip?scale adj package and semiconductor adj die and (etch etching etched) with wafer with anisotropic\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/25 14:46
70	0	chip?scale adj package and (etch etching etched) with wafer with anisotropic\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/25 14:46
71	3356	(etch etching etched) with wafer with anisotropic\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/25 14:47

	Hits	Search Text	DBs	Time Stamp
72	341	(etch etching etched) with wafer with anisotropic\$3 and package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/25 14:47
73	300	(etch etching etched) with wafer with anisotropic\$3 and package and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/25 14:49
74	43	(etch etching etched) with wafer with anisotropic\$3 with (channel trench via opening) and package and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/25 14:51
75	7	(etch etching etched) with wafer with anisotropic\$3 with (channel trench via opening) and package and semiconductor and chip and die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/25 14:51
76	39	(etch etching etched) with wafer with anisotropic\$3 with (channel trench via opening) and package and semiconductor and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/25 14:53
77	70	(etch etching etched) with wafer with anisotropic\$3 same (channel trench via opening) and package and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/25 15:00
78	901	438/113.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/25 15:56
79	212	438/114.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/25 15:56
80	666	438/458.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/25 15:56

	Hits	Search Text	DBs	Time Stamp
81	782	438/460.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/25 15:56
82	235	438/461.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/25 15:56
83	674	438/462.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/25 15:56
84	119	438/463.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/25 15:56
85	1170	438/464.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/25 15:56
86	573	438/465.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/25 15:56
87	626	438/666.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/25 15:56
88	293	438/667.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/25 15:57
89	194	438/668.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/25 15:57

	Hits	Search Text	DBs	Time Stamp
90	1017	438/672.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/25 15:57
91	638	438/675.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/25 15:57